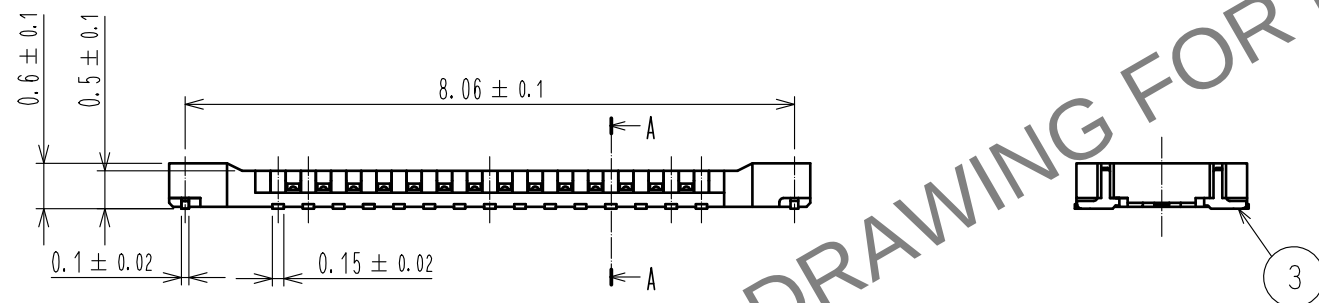
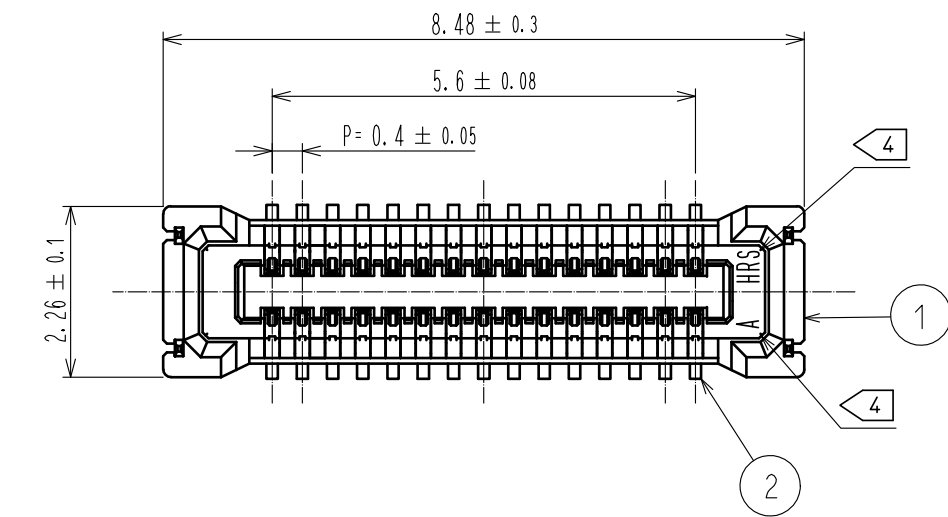


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NOTE 1 . ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX

2 CONTACT PLATING SPECIFICATIONS

CONTACT AREA : GOLD 0.05 μm MIN

SMT LEAD : GOLD 0.05 μm MIN

UNDERPLATING : NICKEL 1 μm MIN

(SURFACE : SEALING)

3 MATA L FITTING PLATING SPECIFICATIONS

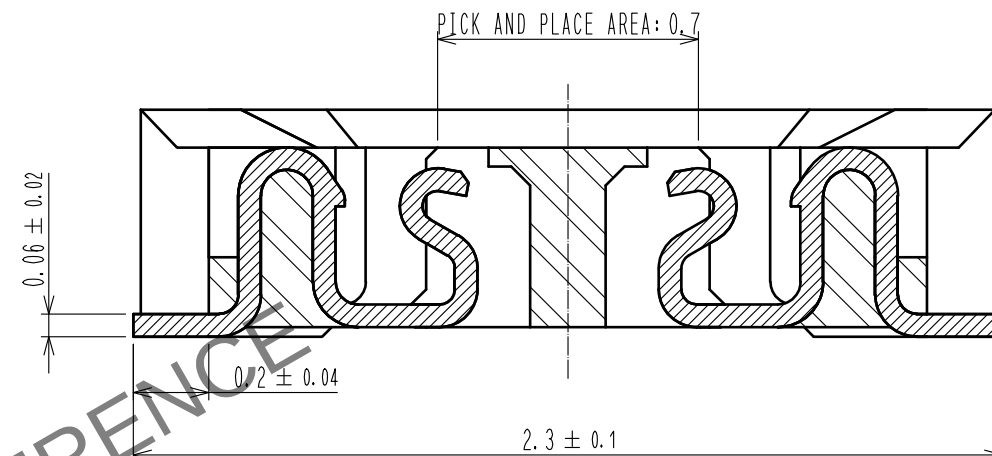
SMT LEAD : GOLD 0.05 μm MIN

UNDERPLATING : NICKEL 1 μm MIN

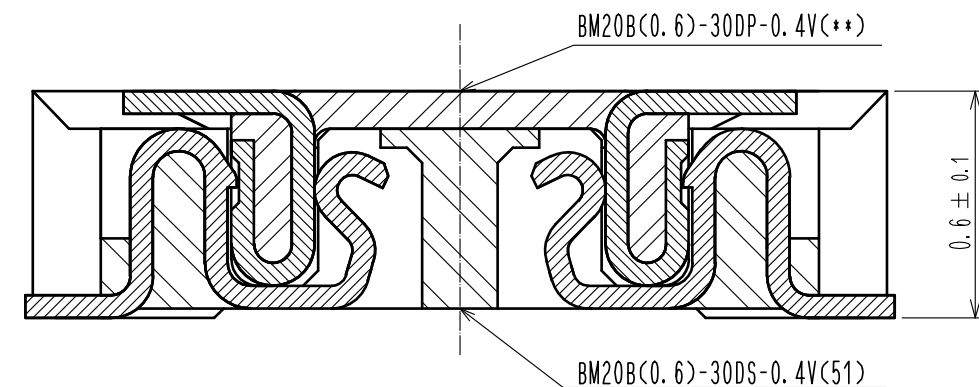
(SURFACE : SEALING)

4 HRS MARK AND CAV NO. ARE INDICATED IN APPROX POSITION SHOWN.

A-A(50:1)



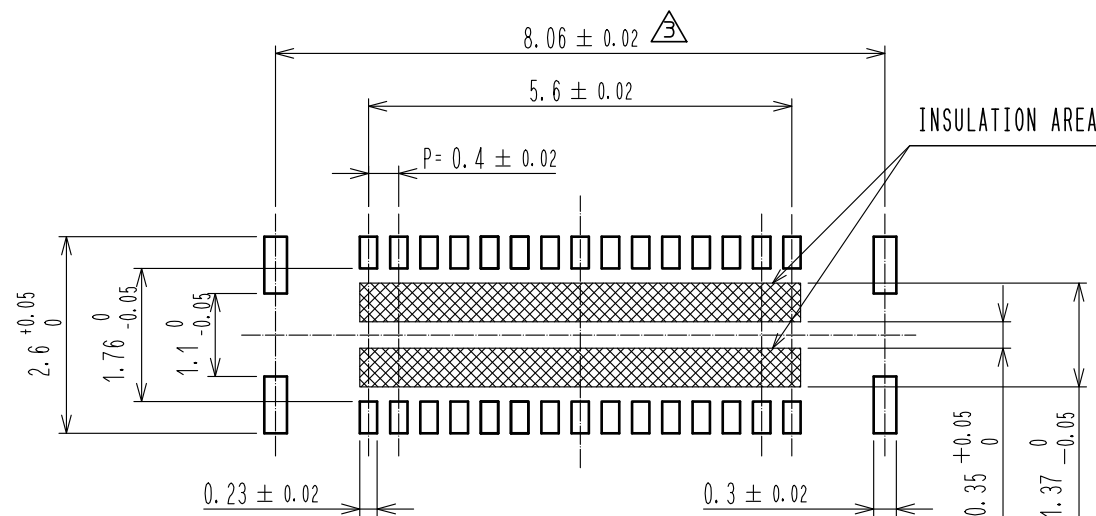
ENGAGEMENT FIGURE (50:1)



4	PS	CLEAR (EMBOSSED CARRIER TAPE)			
3	BRASS	3	7	PS	CLEAR (REINFORCEMENT COLLAR)
2	PHOSPHOR BRONZE	2	6	PS	BLACK (PLASTIC REEL)
1	LCP	UL94 V-0, BLACK	5	POLYESTER	CLEAR (COVER TAPE)
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS
UNITS mm		SCALE 10 : 1	COUNT 3	DESCRIPTION OF REVISIONS DIS-H-00003231	DESIGNED RT. SHIMIZU
HIROSE ELECTRIC CO., LTD.		APPROVED : KH. IKEDA	12.11.19	DRAWING NO.	EDC3-347098-01
		CHECKED : WR. FUKUCHI	12.11.19	PART NO.	BM20B(0.6)-30DS-0.4V(51)
		DESIGNED : RT. SHIMIZU	12.11.19	CODE NO.	CL684-9311-2-51
		DRAWN : YS. YAMAZAKI	12.11.17		
				DATE	17.11.02
				CHECKED	TS. MIYAZAKI

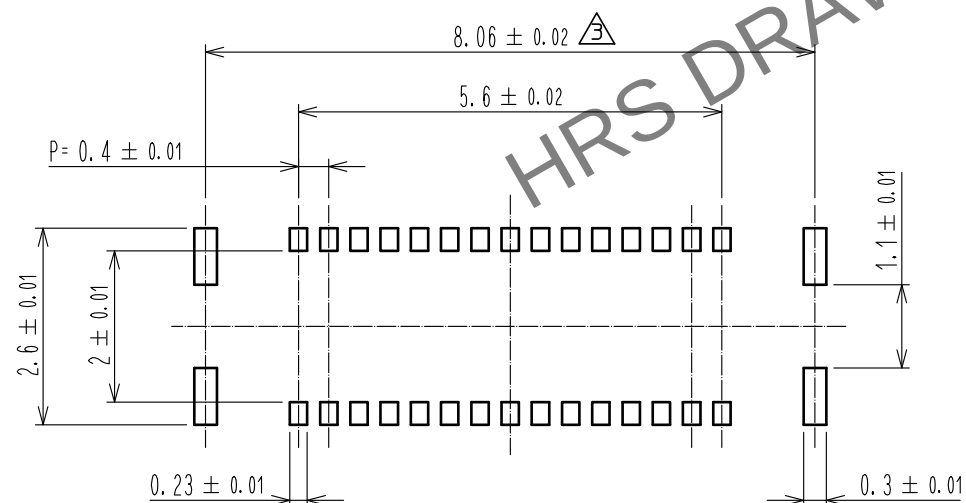
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◆RECOMMENDED PCB LAYOUT

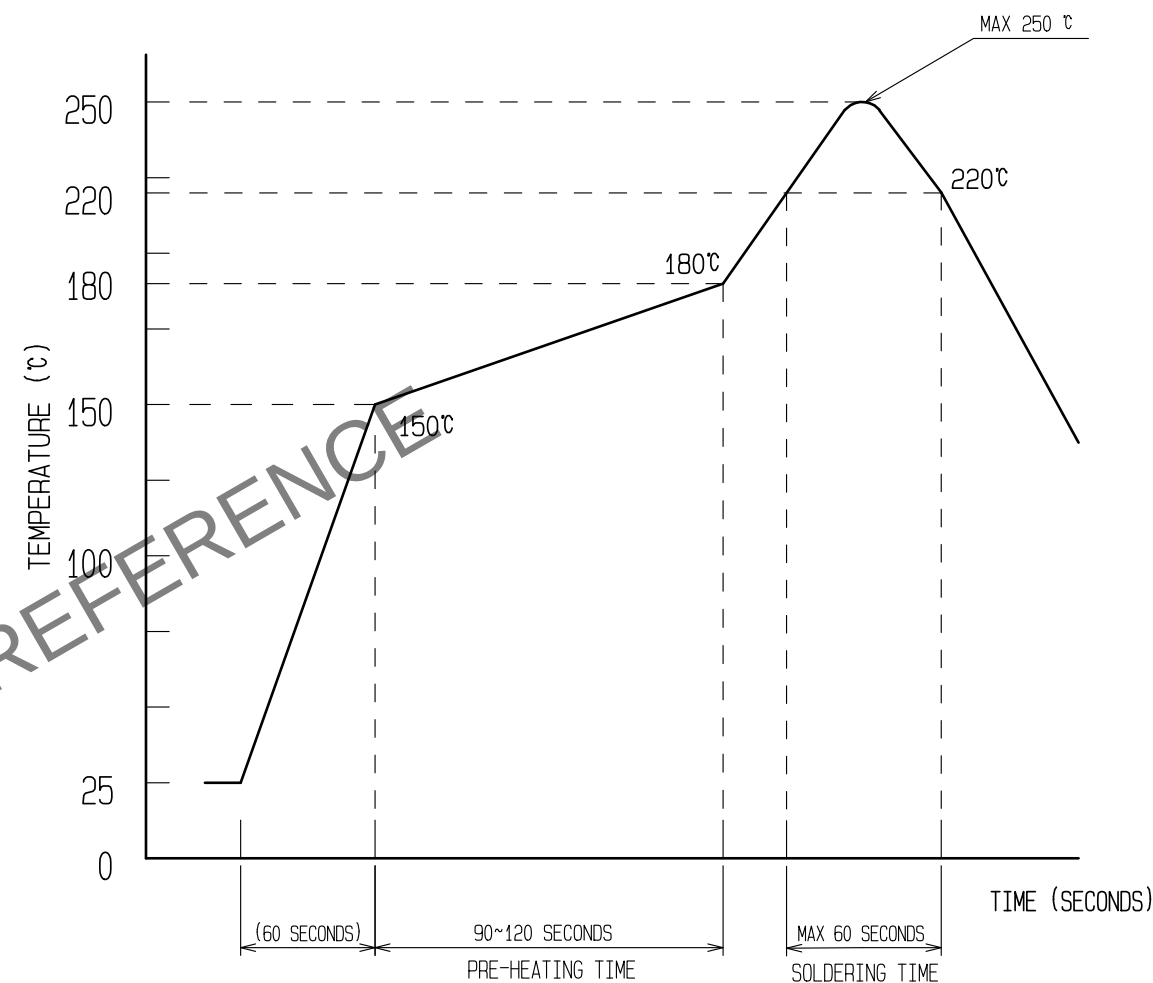


◆RECOMMENDED METAL MASK DIMENSIONS

MATAL MASK THICKNESS : $100 \mu\text{m}$



5 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



- REFLOW METHOD : IR REFLOW
NUMBER OF REFLOW CYCLES : 2 CYCLES MAX.
- 1) REFLOW TIME
DURATION ABOVE 220°C, 60 SEC MAX.
(PEAK TEMPERATURE : 250°C MAX)
 - 2) PRE-HEAT TIME
PRE-HEAT TEMPERATURE(MIN): 150°C
PRE-HEAT TEMPERATURE(MAX): 180°C
PRE-HEAT TIME: 90-120 SEC.

5 THE TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

HRS

DRAWING NO.	EDC3-347098-01
PART NO.	BM20B(0.6)-30DS-0.4V(51)
CODE NO.	CL684-9311-2-51

3/2/3

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